





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
60V	$2\Omega @ V_{GS} = 10V$	380mA
007	3Ω @ V _{GS} = 5V	310mA

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

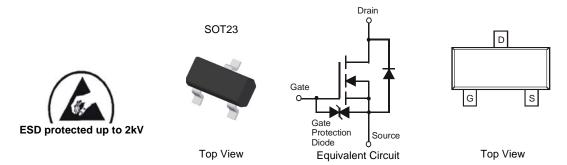
- Motor Control
- Power Management Functions
- Backlighting

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208 ©3
- Weight: 0.008 grams (approximate)



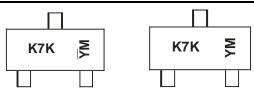
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
2N7002K-7	Standard	SOT23	3000/Tape & Reel
2N7002KQ-7	Automotive	SOT23	3000/Tape & Reel
2N7002K-13	Standard	SOT23	10000/Tape & Reel
2N7002KQ-13	Automotive	SOT23	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



Chengdu A/T Site

K7K = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site) $\overline{Y}M$ = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or \overline{Y} = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Key

Date Code N	,											
Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	T	J	>	W	X	Υ	Z	Α	В	С	D	Е
•												
84 41.												
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Shanghai A/T Site



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units			
Drain-Source Voltage		V_{DSS}	60	V		
Gate-Source Voltage	V _{GSS}	±20	V			
Continuous Prais Compart (Note C) // 40 //	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	380 300	mA	
Continuous Drain Current (Note 6) V _{GS} = 10V	t<5s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	430 340	mA	
Continuous Prain Current (Note 6) // 5/	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	310 240	mA	
Continuous Drain Current (Note 6) V _{GS} = 5V	t<5s	$T_A = +25$ °C $T_A = +70$ °C	l _D	350 270	mA	
Maximum Continuous Body Diode Forward Current (Note 6)			I _S	0.5	А	
Pulsed Drain Current (10µs pulse, duty cycle = 1%	(Note 6)		I _{DM}	1.2	Α	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		P_D	370	mW
Thermal Begistenes, Junction to Ambient (Note 5)	Steady State	D	357	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<5s	$R_{\theta JA}$	292	C/VV
Total Power Dissipation (Note 6)		P_{D}	540	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	5	240	
Thermal Resistance, Junction to Ambient (Note 6)	t<5s	$R_{\theta JA}$	197	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	91	
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

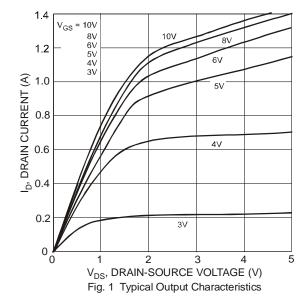
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		ı		ı	ı	
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1.0	μΑ	$V_{DS} = 60V$, $V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)			-			
Gate Threshold Voltage	$V_{GS(th)}$	1.0	1.6	2.5	V	$V_{DS} = 10V$, $I_D = 1mA$
Static Drain-Source On-Resistance			_	2.0	Ω	$V_{GS} = 10V, I_D = 0.5A$
Static Dialii-Source Off-Resistance	R _{DS(ON)}		_	3.0	122	$V_{GS} = 5V, I_D = 0.05A$
Forward Transfer Admittance	Y _{fs}	80	_	_	ms	$V_{DS} = 10V, I_D = 0.2A$
Diode Forward Voltage	V_{SD}	_	0.75	1.1	V	$V_{GS} = 0V, I_S = 115mA$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	30	50	pF	N/ 051/ 1/ 01/
Output Capacitance	C _{oss}	_	4.2	25	pF	$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C_{rss}		2.9	5.0	pF	1 = 1.0lvinz
Gate Resistance	Rg	_	133	_	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$
Total Gate Charge	Qq	_	0.3	_	nC	451/1/
Gate-Source Charge	Qgs	_	0.2	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q _{qd}	_	0.08	_	nC	I _D = 250mA
Turn-On Delay Time	t _{D(on)}	_	3.9	_	ns	
Turn-On Rise Time	t _r	_	3.4	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(off)}	_	15.7	_	ns	$R_G = 25\Omega$, $I_D = 200 \text{mA}$
Turn-Off Fall Time	tf	_	9.9	_	ns	

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
- 7. Short duration pulse test used to minimize self-heating effect.8. Guaranteed by design. Not subject to product testing.





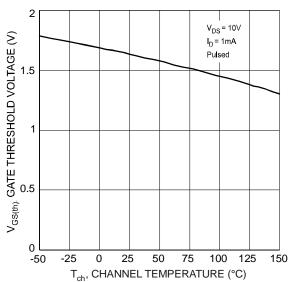


Fig. 3 Gate Threshold Voltage vs. Channel Temperature

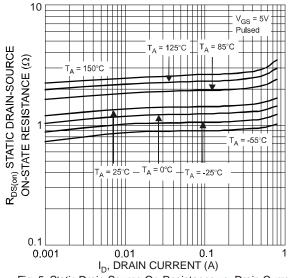
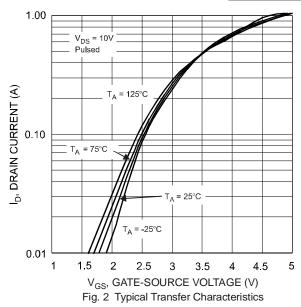


Fig. 5 Static Drain-Source On-Resistance vs. Drain Current



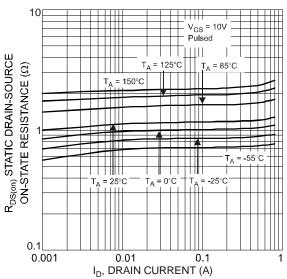


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current

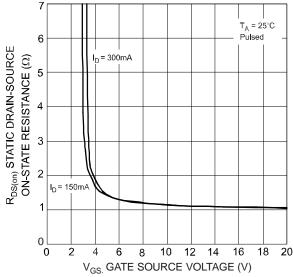
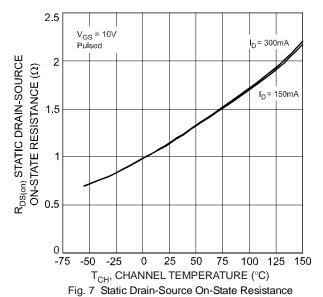
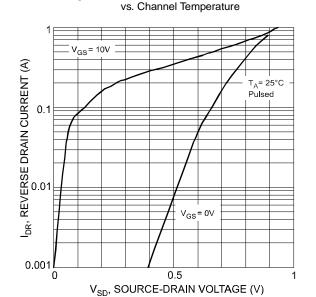
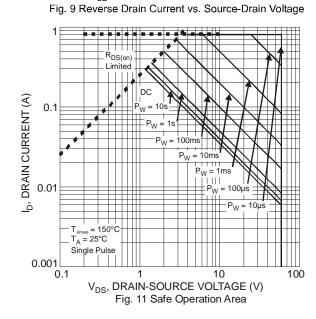


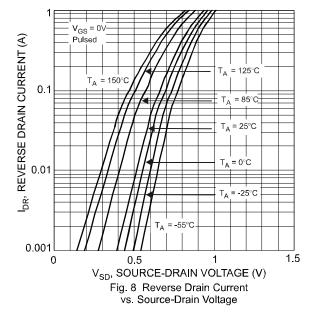
Fig. 6 Static Drain-Source On-Resistance vs. Gate-Source Voltage











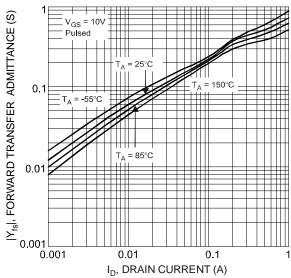
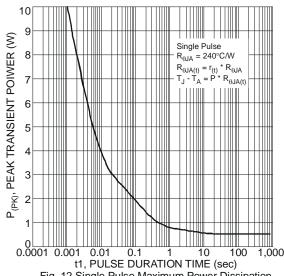
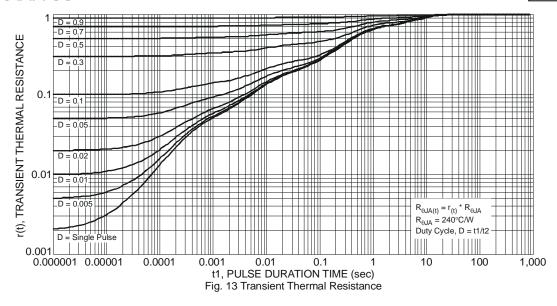


Fig.10 Forward Transfer Admittance vs. Drain Current

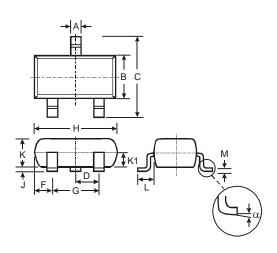






Package Outline Dimensions

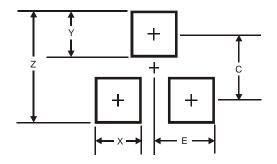
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35



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